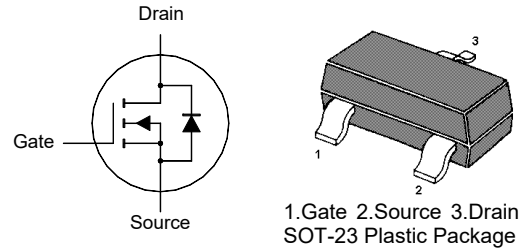


MMBT7002-HAF

N-Channel Enhancement Mode MOSFET

Features

- High density cell design for low $R_{DS(ON)}$
- Voltage controlled small signal switching
- High saturation current capability
- High speed switching
- Halogen and Antimony Free(HAF), RoHS compliant



Applications

- Portable appliances
- Battery management
- High speed switch
- Low power DC to DC Converter

Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

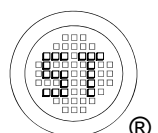
| Parameter | Symbol | Value | Unit |
|--|----------------|---------------|------------------|
| Drain Source Voltage | V_{DSS} | 60 | V |
| Drain Gate Voltage ($R_{GS} \leq 1 \text{ M}\Omega$) | V_{DGR} | 60 | V |
| Gate Source Voltage | V_{GSS} | ± 20 | V |
| | | ± 40 | |
| Drain Current - Continuous | I_D | 300 | mA |
| | | 190 | |
| Peak Drain Current, Pulsed ¹⁾ | I_{DM} | 1.5 | A |
| Total Power Dissipation ²⁾ | P_{tot} | 350 | mW |
| Operating and Storage Temperature Range | T_J, T_{stg} | - 55 to + 150 | $^\circ\text{C}$ |

Thermal Characteristics

| Parameter | Symbol | Max. | Unit |
|--|-----------------|------|--------------------|
| Thermal Resistance - Junction to Ambient ²⁾ | $R_{\theta JA}$ | 357 | $^\circ\text{C/W}$ |

¹⁾ Pulse Test: Pulse Width $\leq 100 \mu\text{s}$, Duty Cycle $\leq 2\%$, Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ\text{C}$.

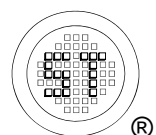
²⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad.



MMBT7002-HAF

Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Min. | Typ. | Max. | Unit |
|--|--------------|--------|--------|---------------|---------------|
| STATIC PARAMETERS | | | | | |
| Drain Source Breakdown Voltage at $I_D = 10\ \mu\text{A}$ | BV_{DSS} | 60 | - | - | V |
| Zero Gate Voltage Drain Current at $V_{DS} = 60\ \text{V}$ | I_{DSS} | - | - | 1 | μA |
| Gate Source Leakage Current at $V_{GS} = \pm 20\ \text{V}$ | I_{GSS} | - | - | ± 100 | nA |
| Gate Source Threshold Voltage at $V_{DS} = V_{GS}$, $I_D = 250\ \mu\text{A}$ | $V_{GS(th)}$ | 1 | - | 2.5 | V |
| Static Drain Source On Resistance at $V_{GS} = 10\ \text{V}$, $I_D = 500\ \text{mA}$ | $R_{DS(ON)}$ | - | - | 5 | Ω |
| Drain Source On Voltage at $V_{GS} = 5\ \text{V}$, $I_D = 50\ \text{mA}$ at $V_{GS} = 10\ \text{V}$, $I_D = 500\ \text{mA}$ | $V_{DS(ON)}$ | - - | - - | 0.375 3.75 | V |
| DYNAMIC PARAMETERS | | | | | |
| Forward Transconductance at $V_{DS} = 10\ \text{V}$, $I_D = 200\ \text{mA}$ | g_{FS} | 80 | - | - | mS |
| Input Capacitance at $V_{DS} = 25\ \text{V}$, $f = 1\ \text{MHz}$ | C_{iss} | - | 22.5 | 50 | pF |
| Output Capacitance at $V_{DS} = 25\ \text{V}$, $f = 1\ \text{MHz}$ | C_{oss} | - | 9 | 25 | pF |
| Reverse Transfer Capacitance at $V_{DS} = 25\ \text{V}$, $f = 1\ \text{MHz}$ | C_{rss} | - | 7.5 | 10 | pF |
| Total Gate Charge at $V_{DS} = 30\ \text{V}$, $I_D = 0.2\ \text{A}$, $V_{GS} = 10\ \text{V}$ | Q_g | - | 1.08 | - | nC |
| Gate Source Charge at $V_{DS} = 30\ \text{V}$, $I_D = 0.2\ \text{A}$, $V_{GS} = 10\ \text{V}$ | Q_{gs} | - | 0.28 | - | nC |
| Gate Drain Charge at $V_{DS} = 30\ \text{V}$, $I_D = 0.2\ \text{A}$, $V_{GS} = 10\ \text{V}$ | Q_{gd} | - | 0.09 | - | nC |
| Turn-On Delay Time at $V_{DD} = 30\ \text{V}$, $R_L = 150\ \Omega$, $I_D = 0.2\ \text{A}$, $V_{GS} = 10\ \text{V}$, $R_{GEN} = 25\ \Omega$ | $t_{d(on)}$ | - | 2.7 | - | ns |
| Turn-On Rise Time at $V_{DD} = 30\ \text{V}$, $R_L = 150\ \Omega$, $I_D = 0.2\ \text{A}$, $V_{GS} = 10\ \text{V}$, $R_{GEN} = 25\ \Omega$ | t_r | - | 17 | - | ns |
| Turn-Off Delay Time at $V_{DD} = 30\ \text{V}$, $R_L = 150\ \Omega$, $I_D = 0.2\ \text{A}$, $V_{GS} = 10\ \text{V}$, $R_{GEN} = 25\ \Omega$ | $t_{d(off)}$ | - | 8.5 | - | ns |
| Turn-Off Fall Time at $V_{DD} = 30\ \text{V}$, $R_L = 150\ \Omega$, $I_D = 0.2\ \text{A}$, $V_{GS} = 10\ \text{V}$, $R_{GEN} = 25\ \Omega$ | t_f | - | 28 | - | ns |
| Body-Diode PARAMETERS | | | | | |
| Drain-Source Diode Forward Voltage at $V_{GS} = 0\ \text{V}$, $I_S = 0.5\ \text{A}$ | V_{SD} | - | - | 1.2 | V |
| Body Diodes Continuous Current | I_S | - | - | 300 | mA |



Electrical Characteristics Curves

Fig. 1 Output Characteristics

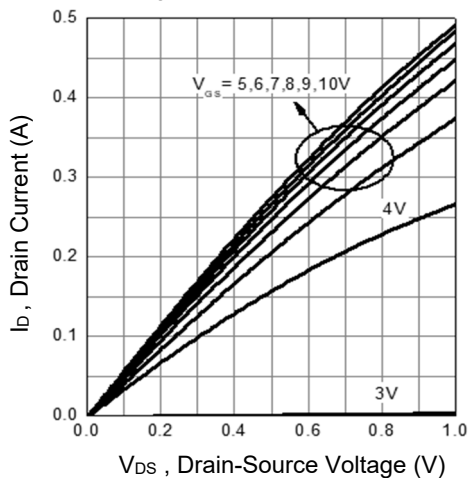


Fig. 2 Transfer Characteristics

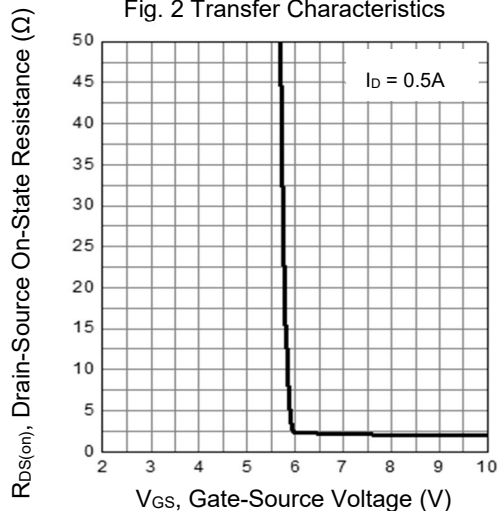


Fig. 3 on-Resistance vs. Drain Current

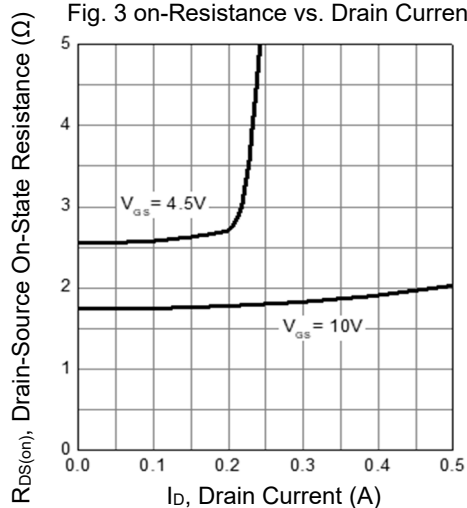


Fig. 4 Body Diode Forward Characteristics

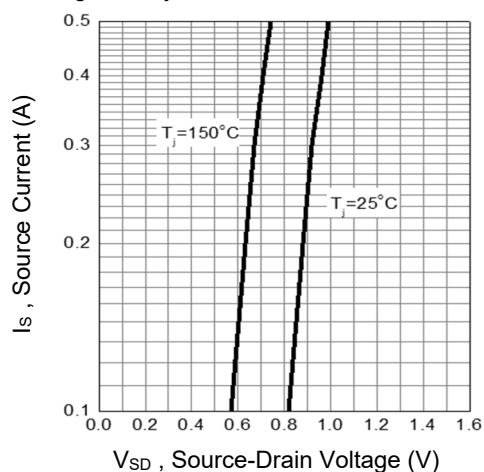


Fig. 5 $R_{DS(on)}$ vs. T_J

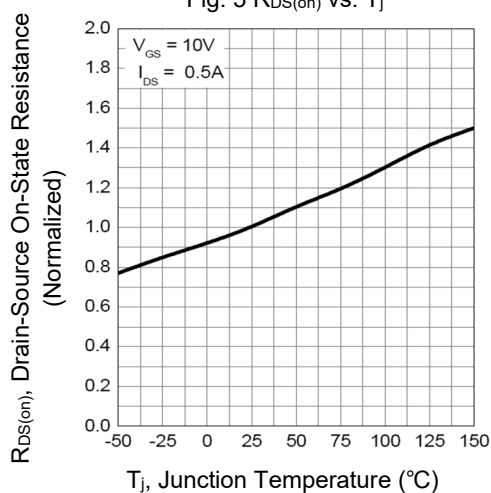
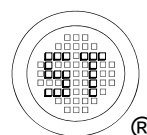
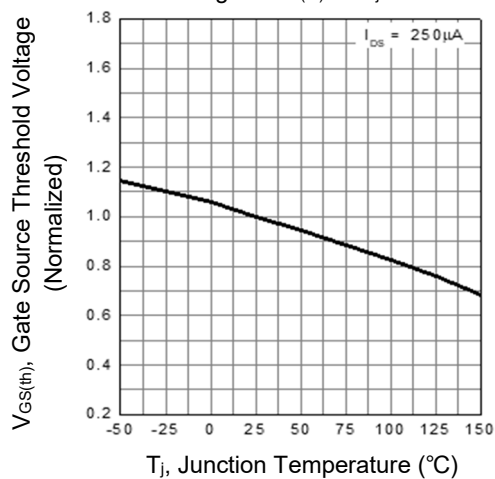
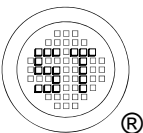
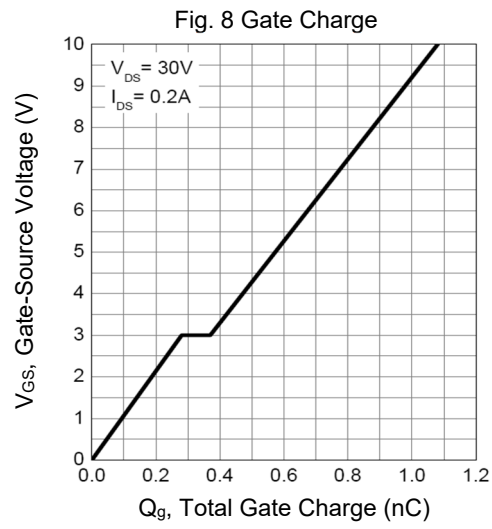
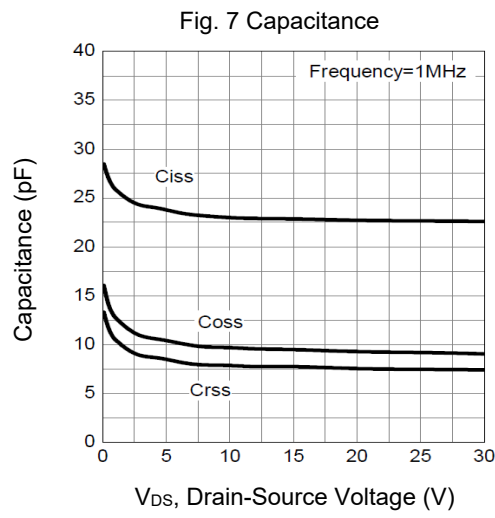


Fig. 6 $V_{GS(th)}$ vs T_J



Electrical characteristic curve



Test Circuits

Fig.1-1 Switching times test circuit

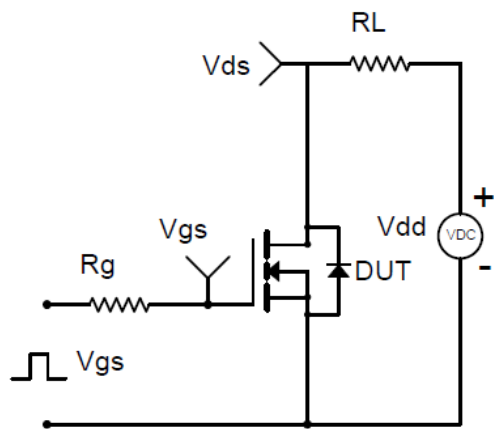


Fig.1-2 Switching Waveform

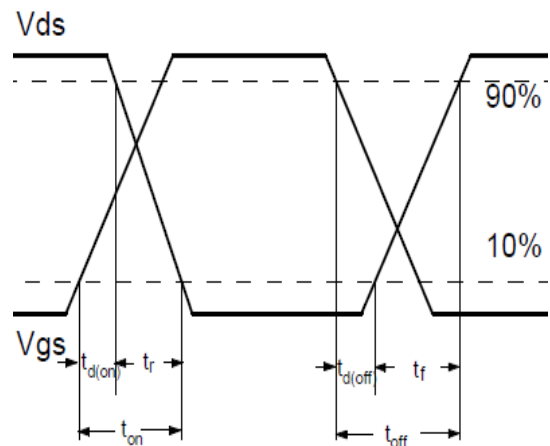


Fig.2-1 Gate charge test circuit

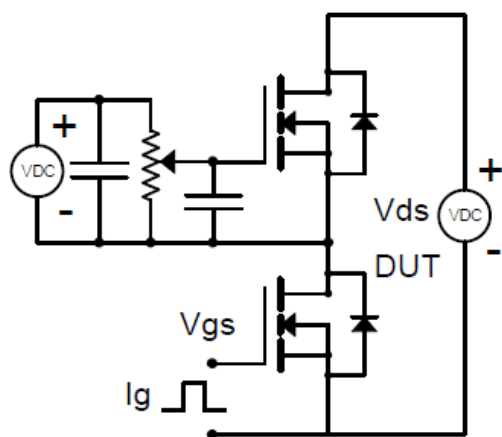
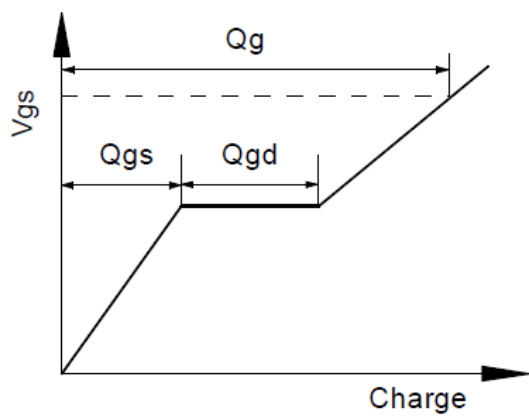


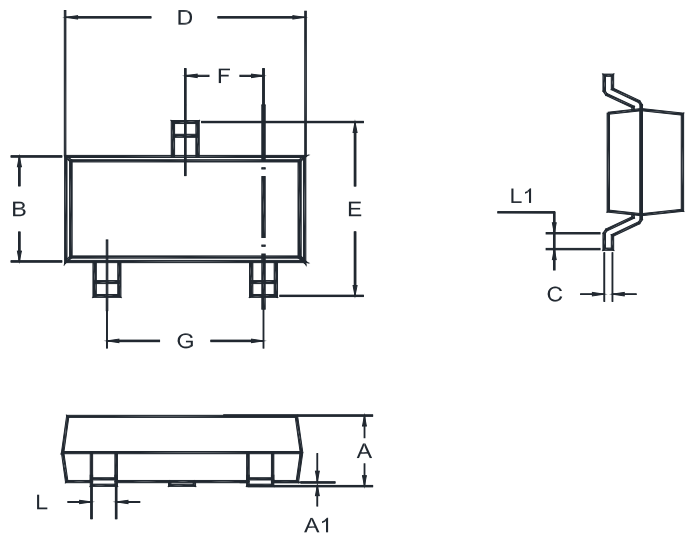
Fig.2-2 Gate charge waveform



MMBT7002-HAF

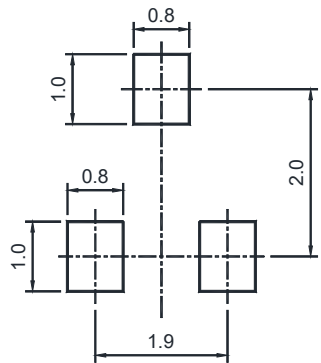
Package Outline (Dimensions in mm)

SOT-23



| Unit | A | A1 | B | C | D | E | F | G | L | L1 |
|------|------|-------|------|------|------|-----|------|------|------|-----|
| mm | 1.20 | 0.100 | 1.40 | 0.19 | 3.04 | 2.6 | 1.02 | 2.04 | 0.51 | 0.2 |
| | 0.89 | 0.013 | 1.20 | 0.08 | 2.80 | 2.2 | 0.89 | 1.78 | 0.37 | MIN |

Recommended Soldering Footprint



Packing information

| Package | Tape Width (mm) | Pitch | | Reel Size | | Per Reel Packing Quantity |
|---------|-----------------|---------|---------------|-----------|------|---------------------------|
| | | mm | inch | mm | inch | |
| SOT-23 | 8 | 4 ± 0.1 | 0.157 ± 0.004 | 178 | 7 | 3,000 |

Marking information

" S72 " = Part No.
" • " = HAF (Halogen and Antimony Free)
" YM " = Date Code Marking
" Y " = Year
" M " = Month
Font type: Arial

